

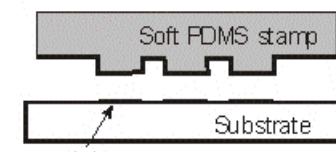
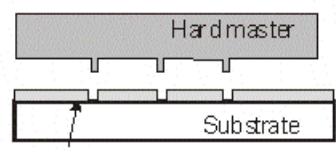
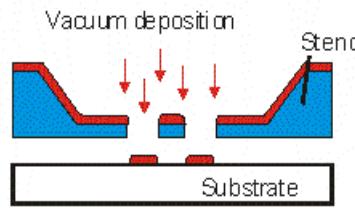


Patterning at
nanoscale:
mCP, NIL and
stenciling

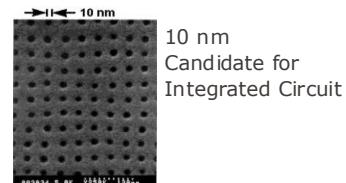
Micro-530

Emerging Nanopatterning Methods

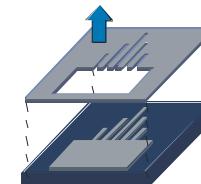
(Replication)

Soft-lithography	Nanoimprint lithography	Nanostencil lithography
Ink delivery molecules, wet <i>soft-contact</i>	Thermo-mechanical, nano-imprinting, <i>hard contact</i>	Local deposition stencil, vacuum <i>no contact</i>
		

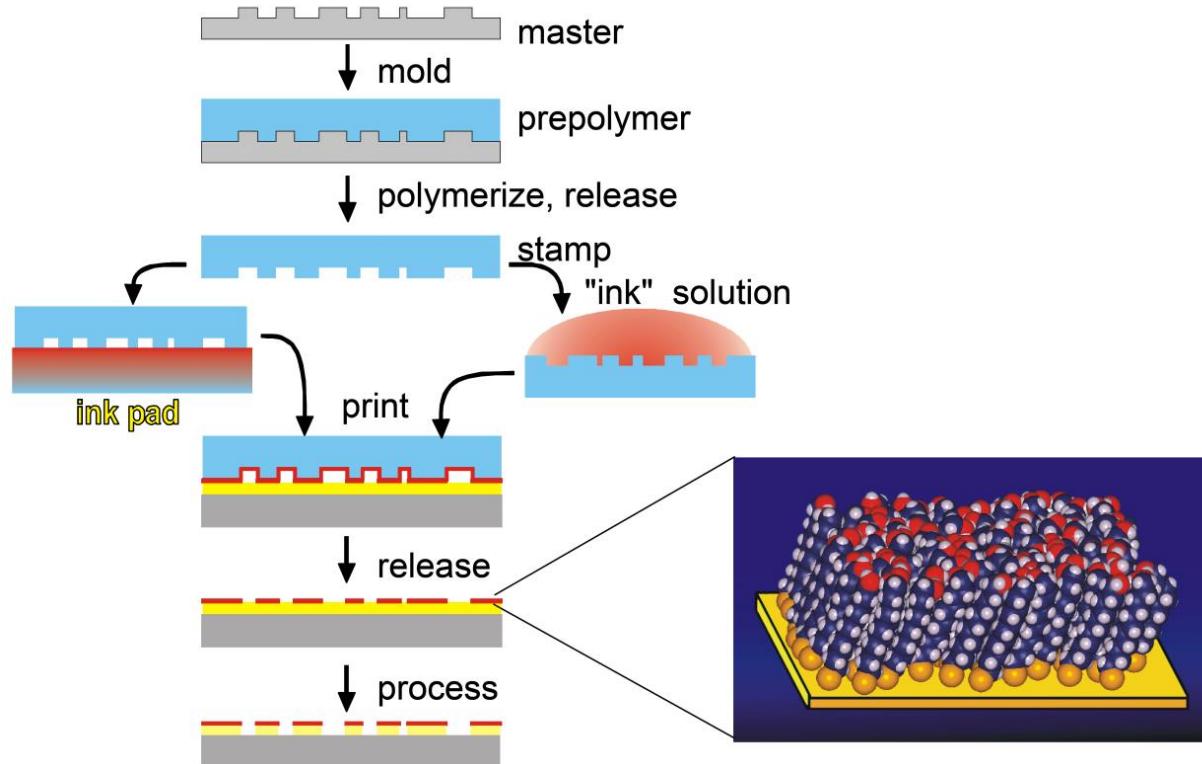




10 nm
Candidate for
Integrated Circuit



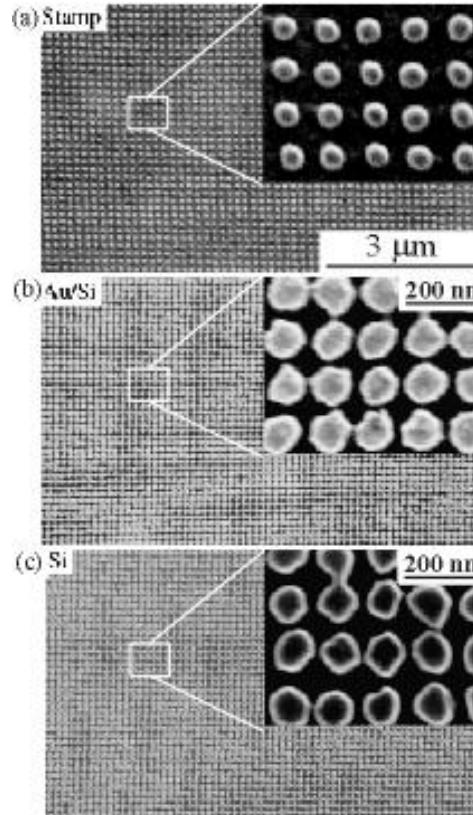
Microcontact Printing (μ CP)



Microcontact Printing

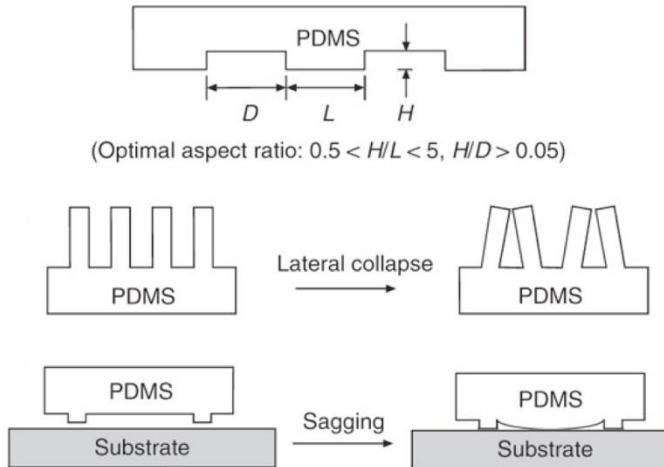
High-resolution μ CP:

- a) Scanning electron micrograph of a stamp with 60 nm dots.
- b) The corresponding gold dots fabricated by printing and etching were slightly broadened due to ink diffusion and substrate roughness.
- c) The gold pattern served as a mask to etch the bare regions 250 nm deep into the underlying silicon by reactive ion etching.



Microcontact Printing

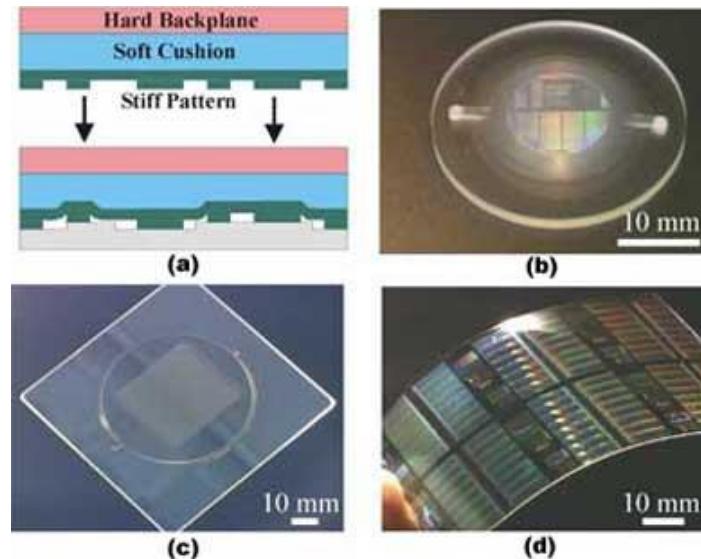
- Possible problems and limitations
- Aspect ratio of stamp features
- Lateral collapse
- Sagging



Microcontact Printing

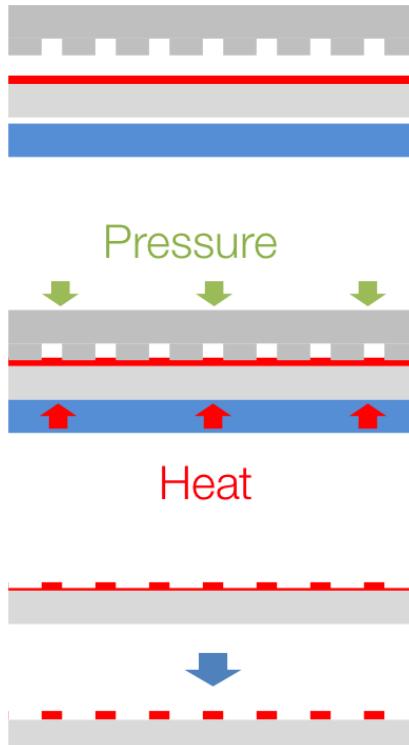
Examples of layered hybrid stamps:

- a) Scheme of trilayer stamp (hard backplane, elastomeric cushion, hard polymer) showing improved adaptation to an uneven substrate
- b) Trilayer stamp with 270 nm features
- c) Bilayer stamp with 5 μm features on a 125 mm glass plate
- d) Example of a two layer, thin film stamp composed of a 100 μm glass backplane and a 30 μm polymer film with 270 nm features.



[From B. Michel, H. Schmid, *Macromolecules* 33 (2000) 3042].

Nano-Imprint Lithography



Imprint stack preparation

Stamp (or mold), Resist, Substrate, Chuck

Imprinting

Pressure / temperature / time profile

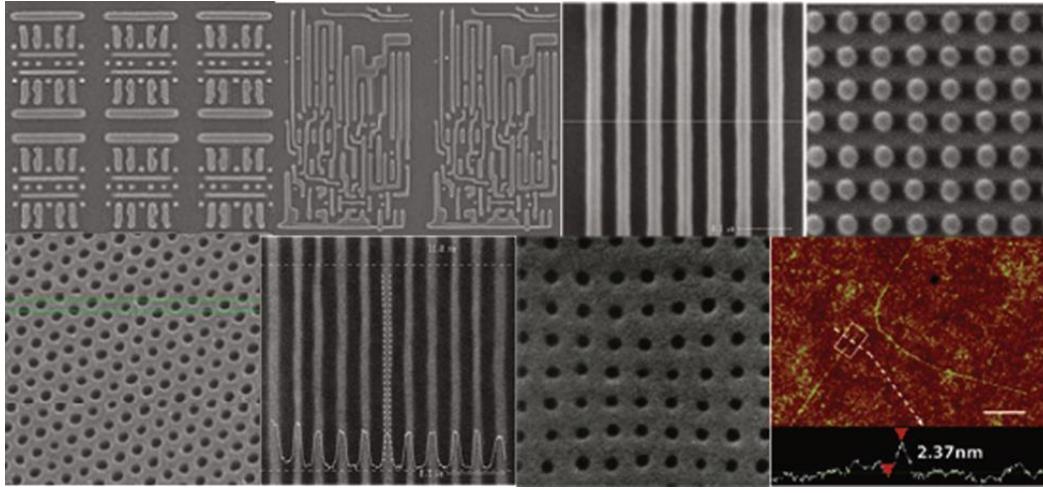
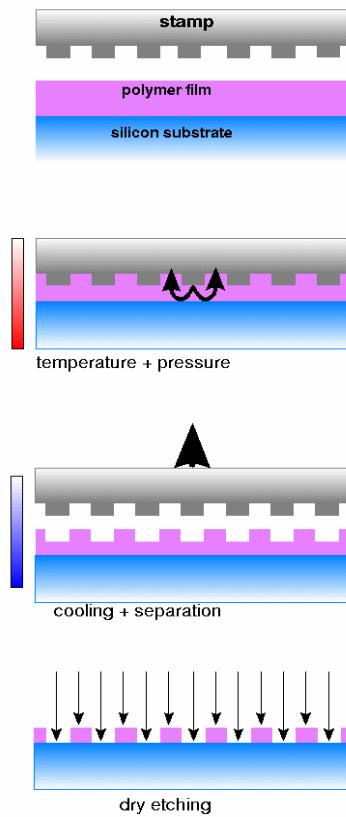
Separation

Temp control

Residual layer etch

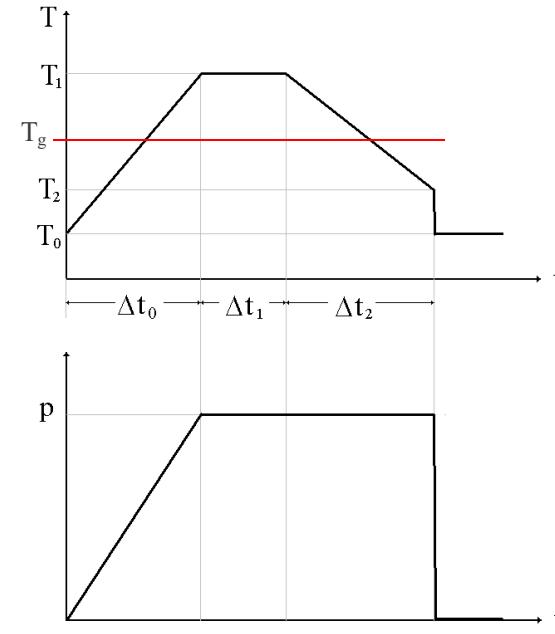
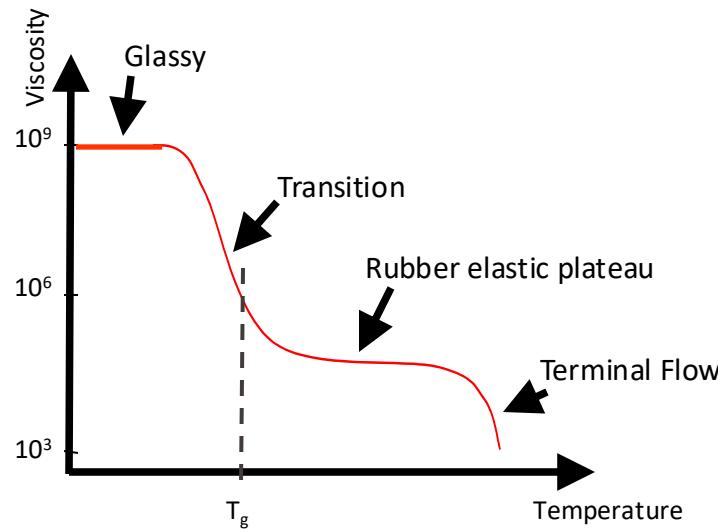
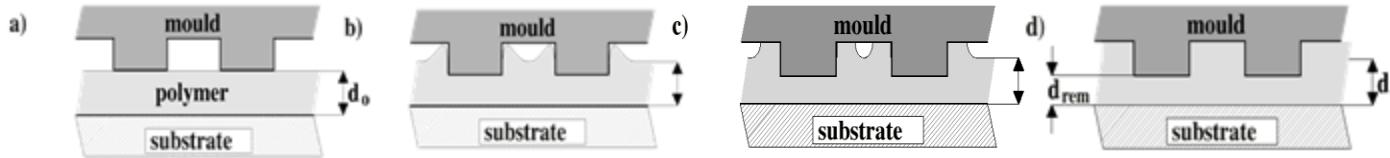
Remove thin resist layer by O₂ plasma

Nano-Imprint Lithography

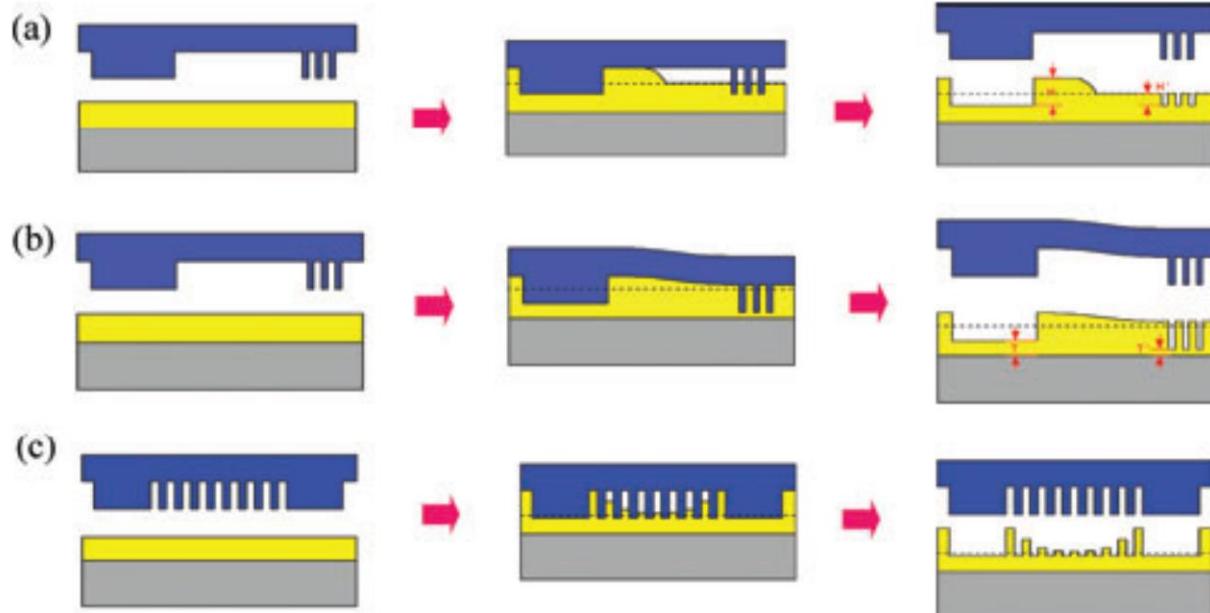


S. Chou et al. *Science* 5 April 1996: Vol. 272 no. 5258 pp. 85-87

Nanoimprint Process Model



Issues with thermal NIL

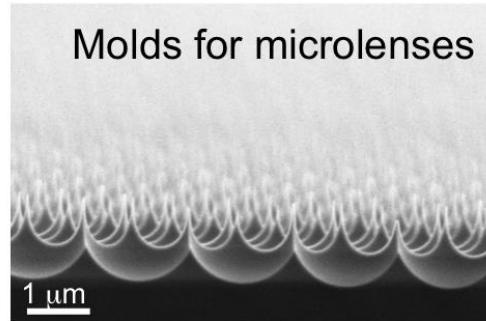
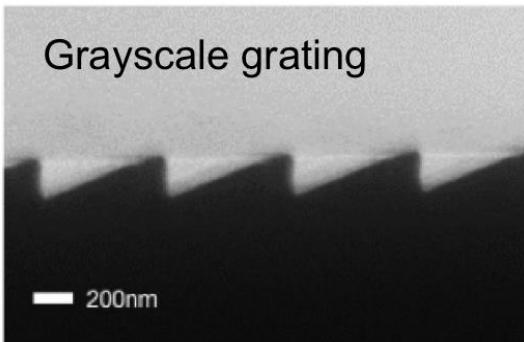
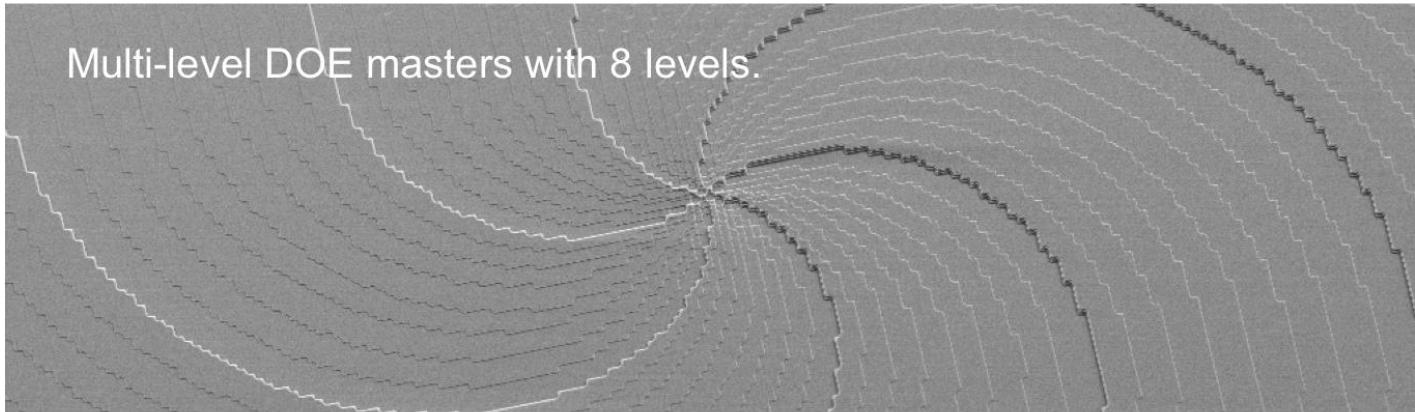


NIL examples

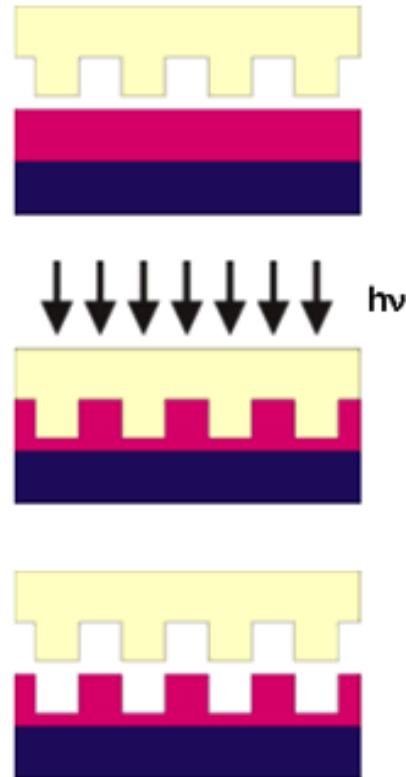
- Master stamp is costly
- Replicate master in working stamp
- Use working stamp for substrate imprinting and for mass fabrication
- Working stamp can be Nickel, Polymer, etc.

<https://www.nilt.com/>

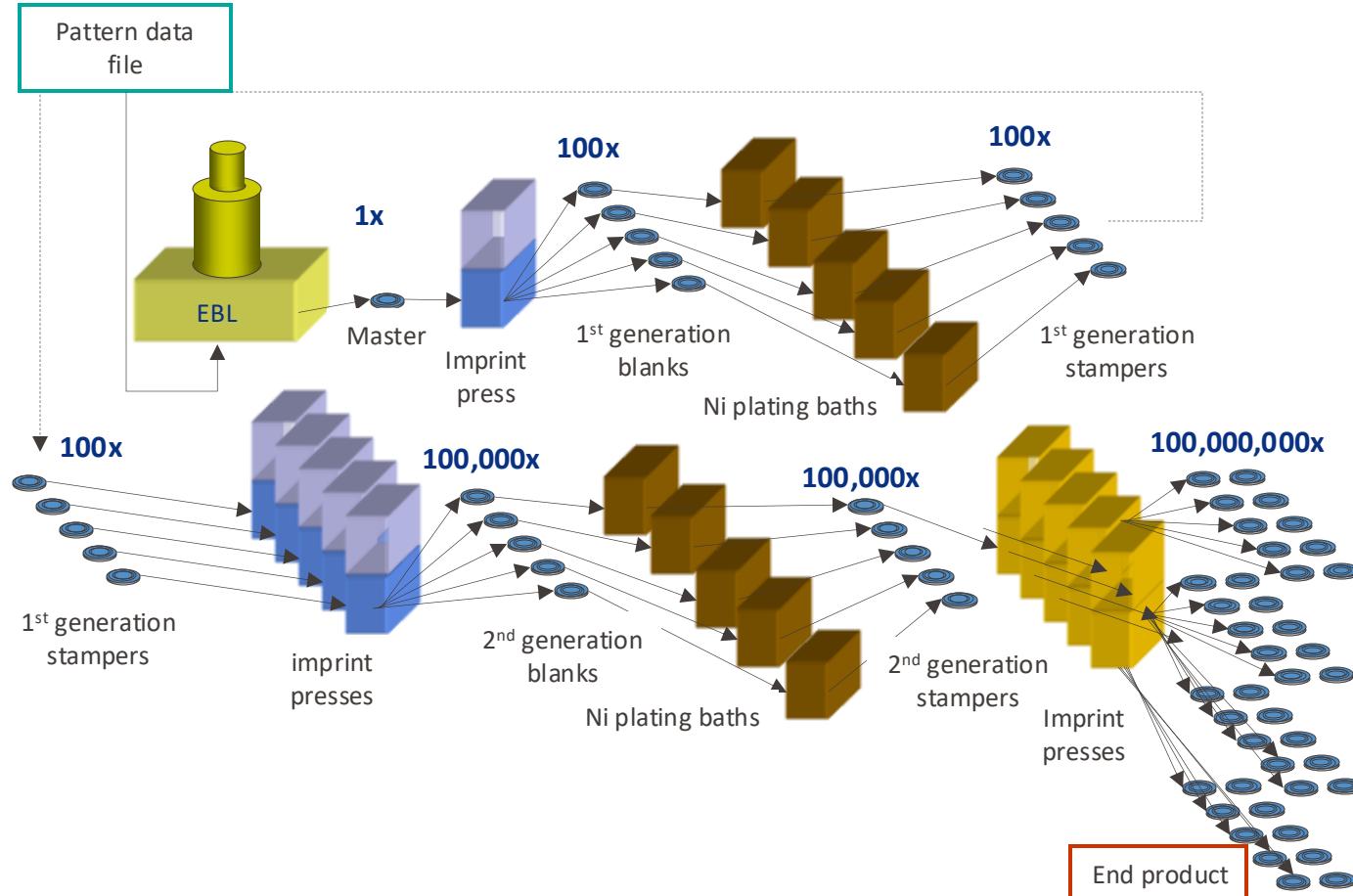
NIL examples



- UV nanoimprint based on liquid polymer

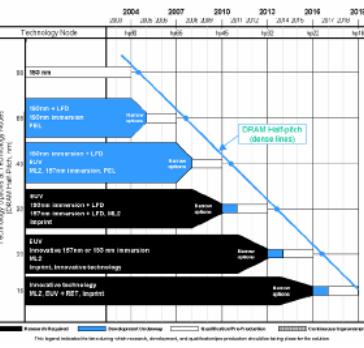
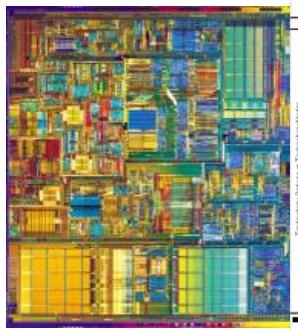


NIL in Mass Production

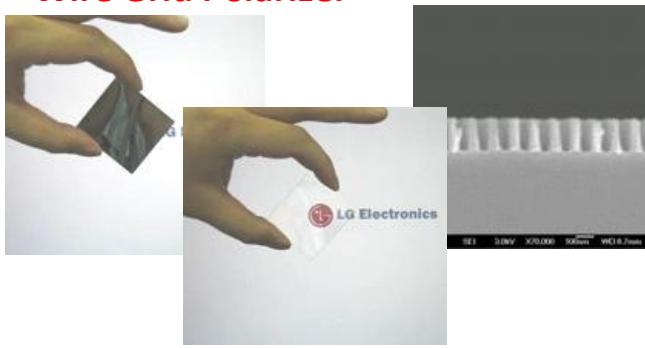


Nanopatterning – Main NIL Applications

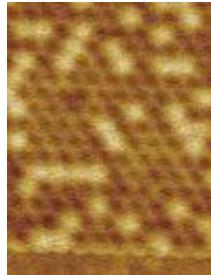
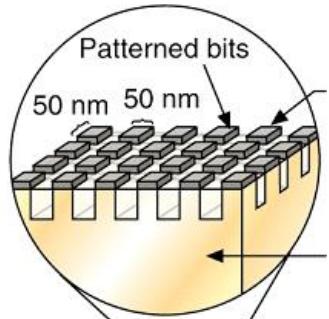
High End Microelectronic Chips



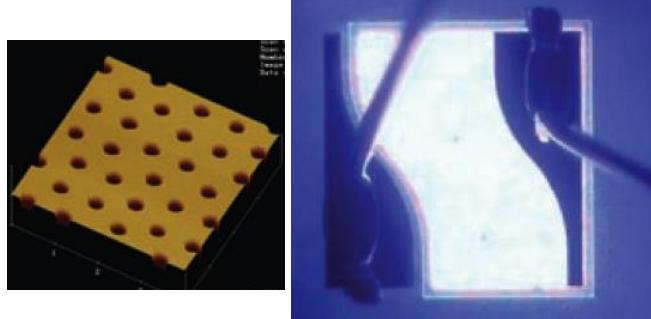
Wire Grid Polarizer



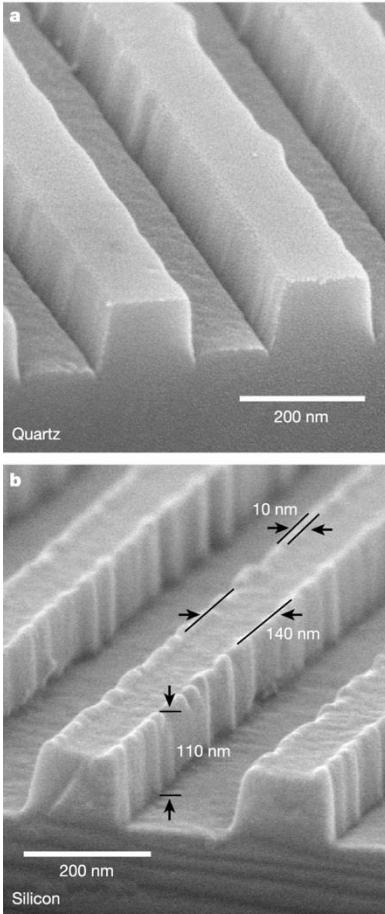
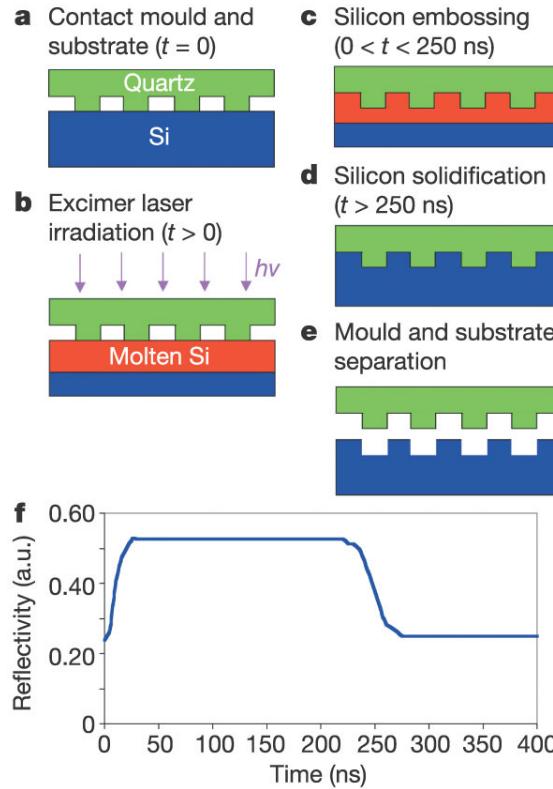
Patterned Magnetic Media



High Brightness LEDs



Direct printing into silicon

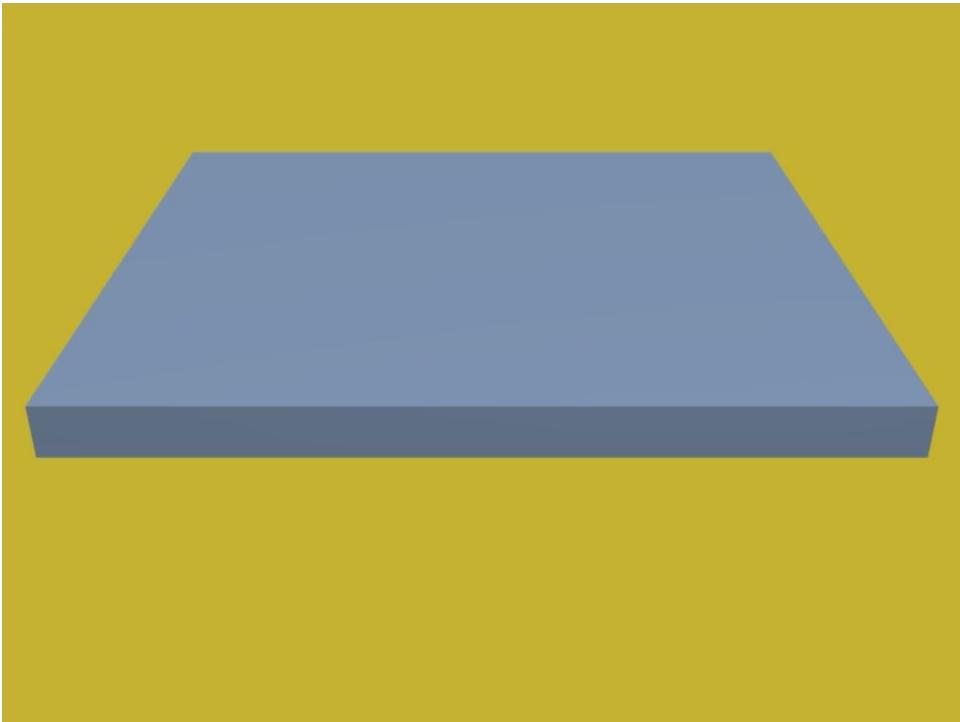




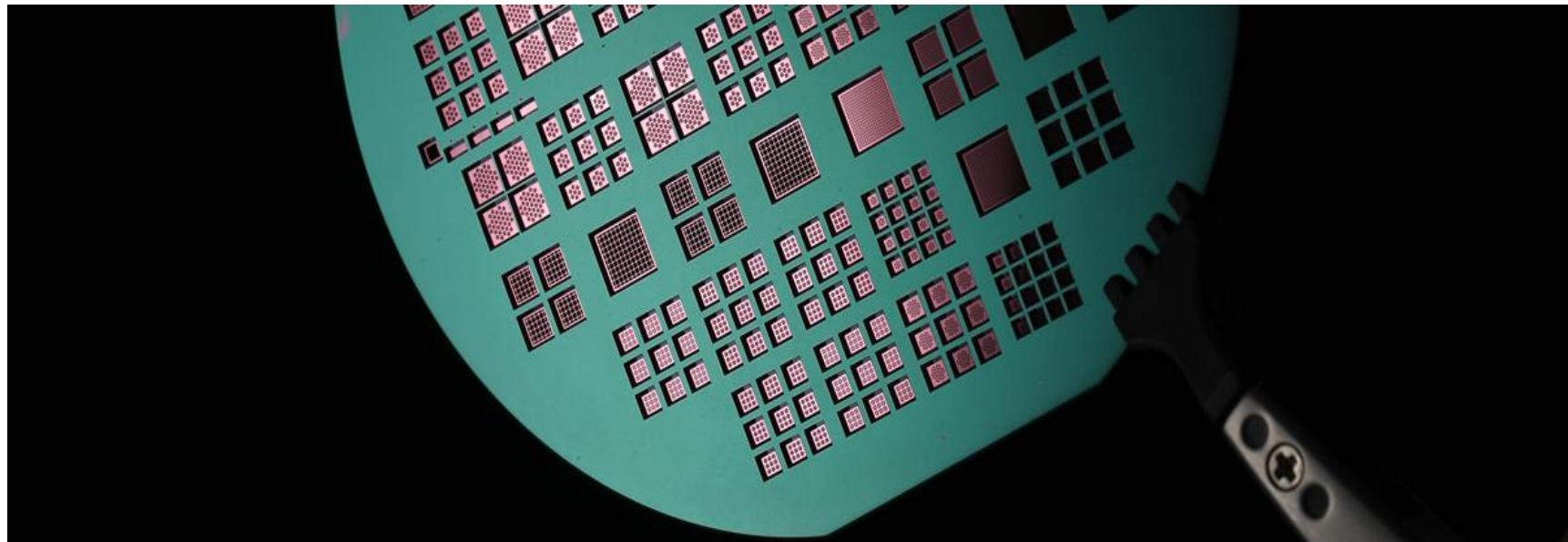
Patterning at nanoscale: Nanostencil Lithography

Micro-530

Stencil lithography (cartoon)



- Patterning without photoresist
- Very small (<100nm)
- Very large (mm)
- Vacuum clean
- Deposition
- Etching
- Implantation



Challenges:

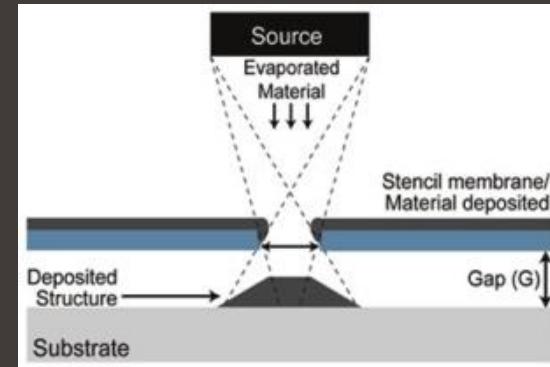
- Gap
- Blurring
- Membrane stability
- Alignment

Opportunities:

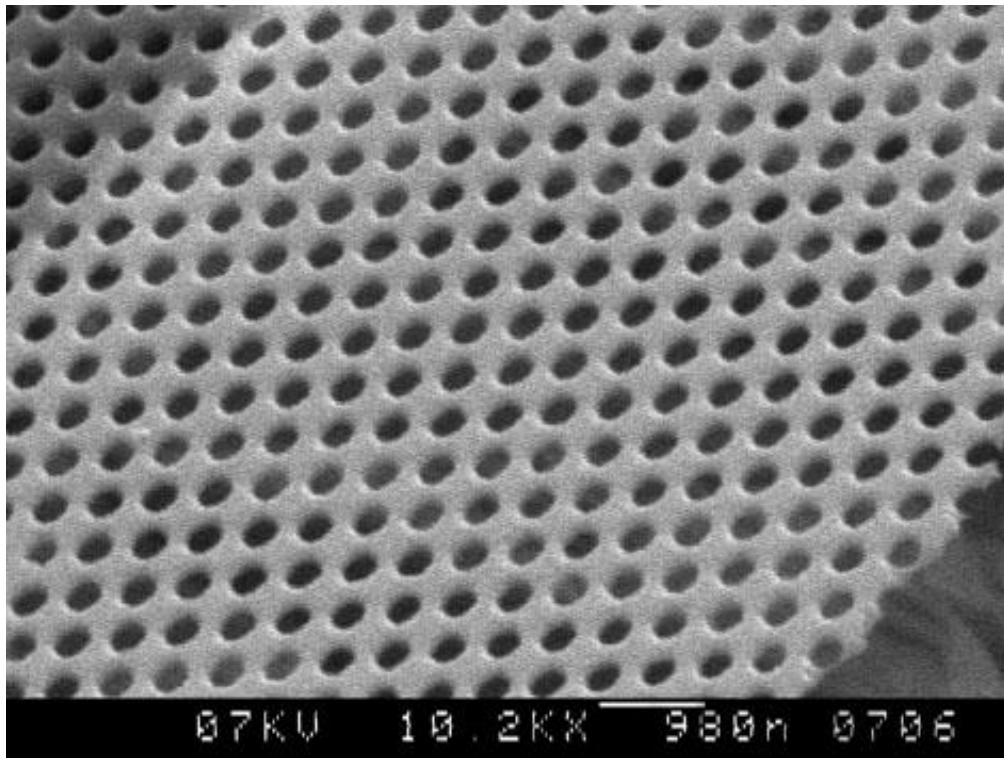
- Vacuum clean
- No resist chemistry
- Fast and simple
- Cost efficient nanofabrication
- Wide choice of material & substrates
- Mainly for PVD, but also ion implantation and dry etching

What are the challenges?

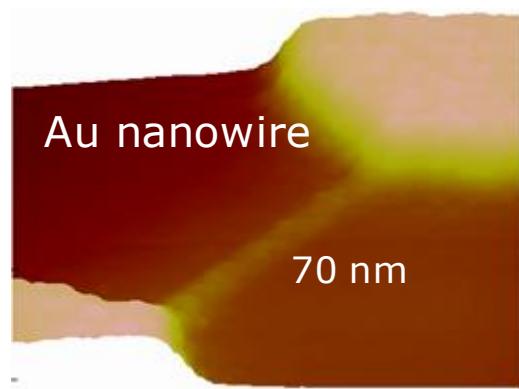
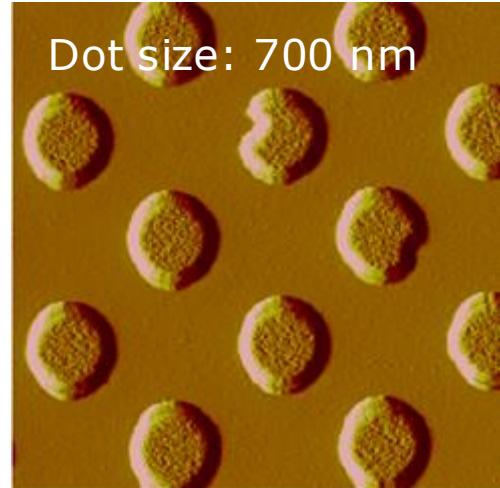
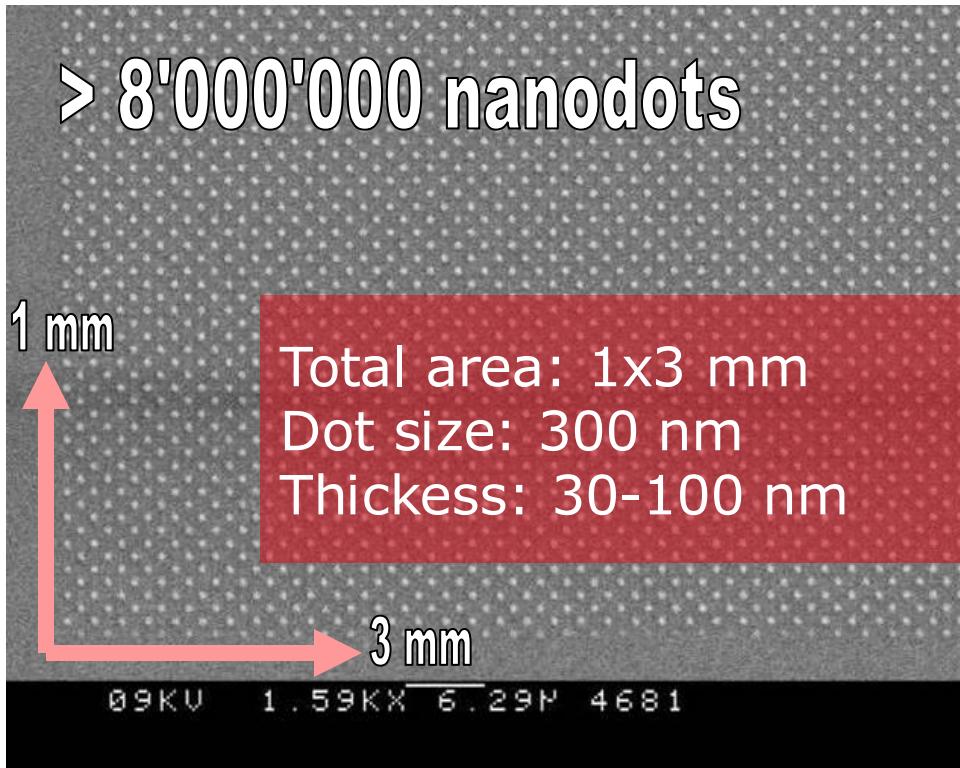
What are the opportunities?



Nanosieves as stencils



Scalable nanostencil ... large membranes



Stencil fabrication

LPCVD 50-500 nm thick SiN

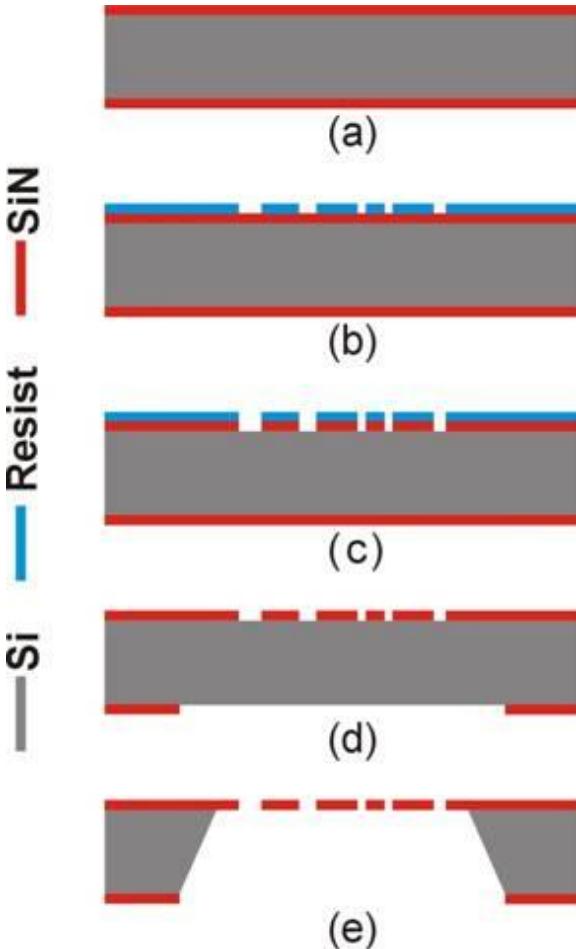
Pattern definition in photoresist

Pattern transfer into SiN

Membrane window definition and KOH etching

Fabrication of nanoscale apertures in membrane by:

- Focused Ion Beam Milling
- Electron beam lithography
- Laser interference lithography
- Nanoimprint lithography
- Deep UV lithography



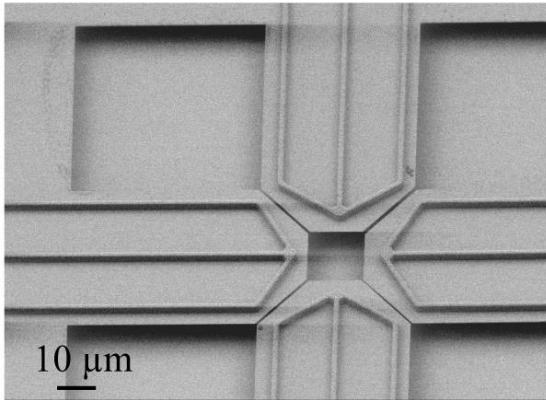
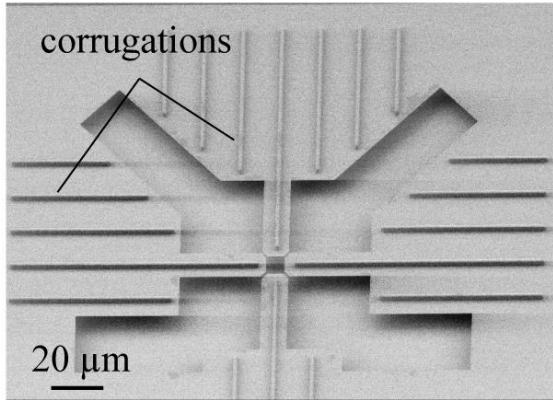
It can go wrong



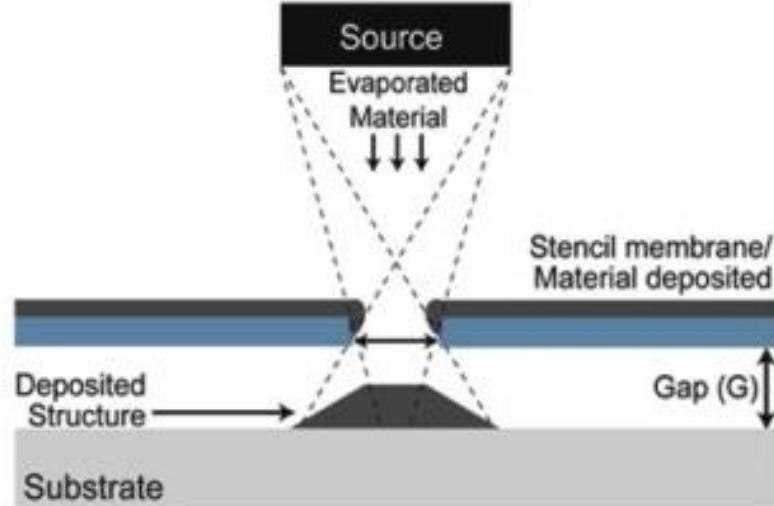
— 200 μm

— 500 μm

Increase moment of inertia to stabilize thin membranes



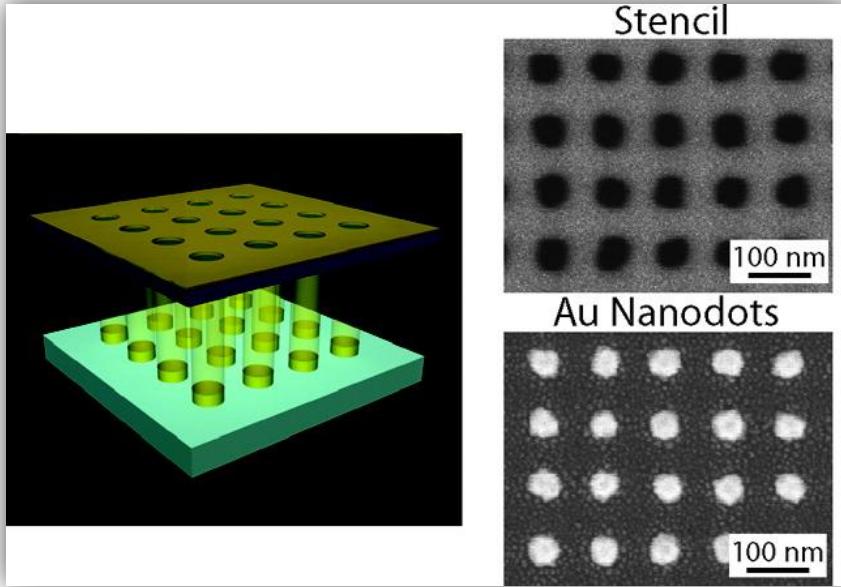
▪ Van den Boogaart et al. 2008



Challenge:
Gap between stencil
and substrate

Compare it to **Lift off**: resist is in contact with substrate; no lateral diffusion

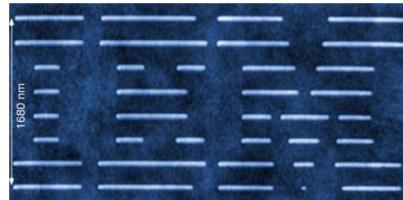
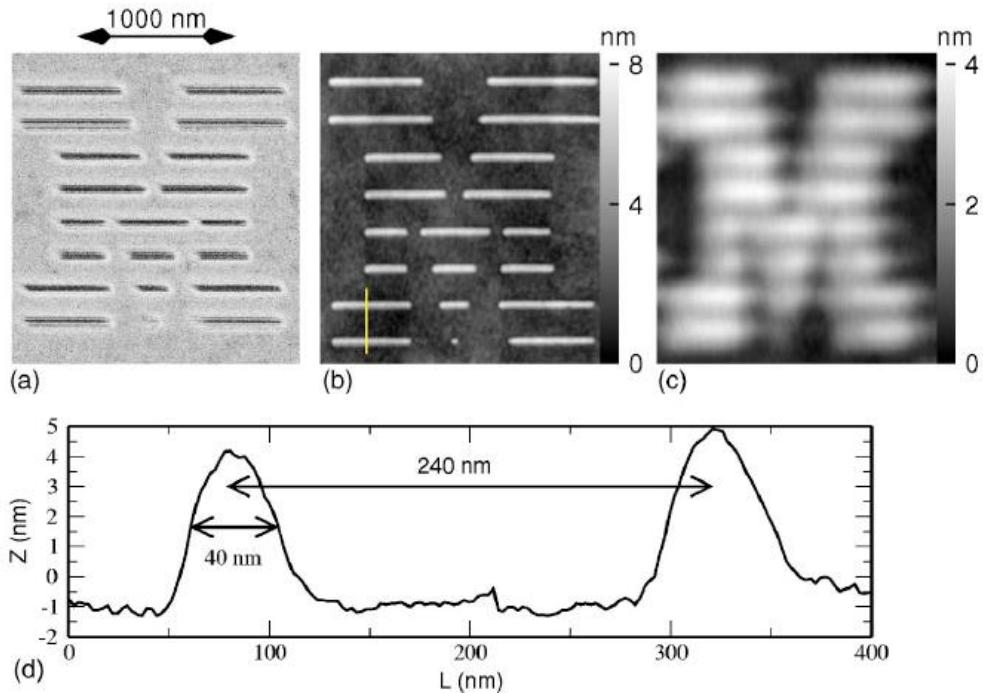




5 nm Ti / 50 nm Au
On Si/SiO₂

Blurring of pattern

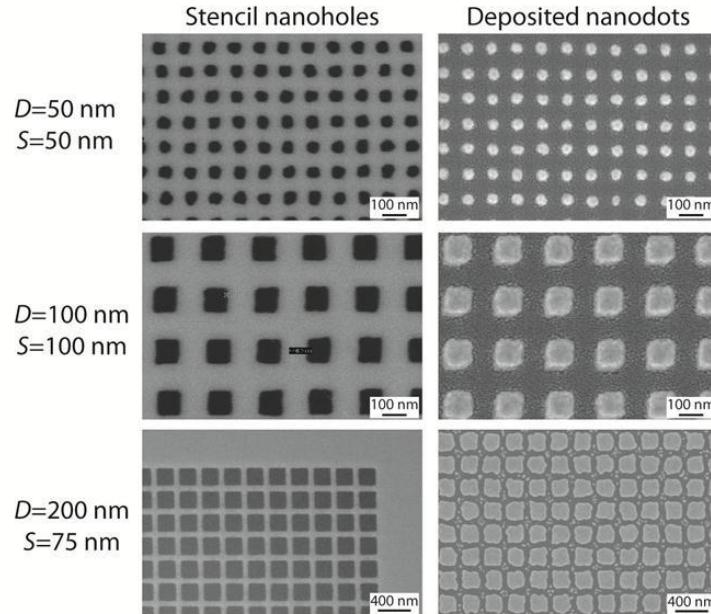
Watch out for surface diffusion



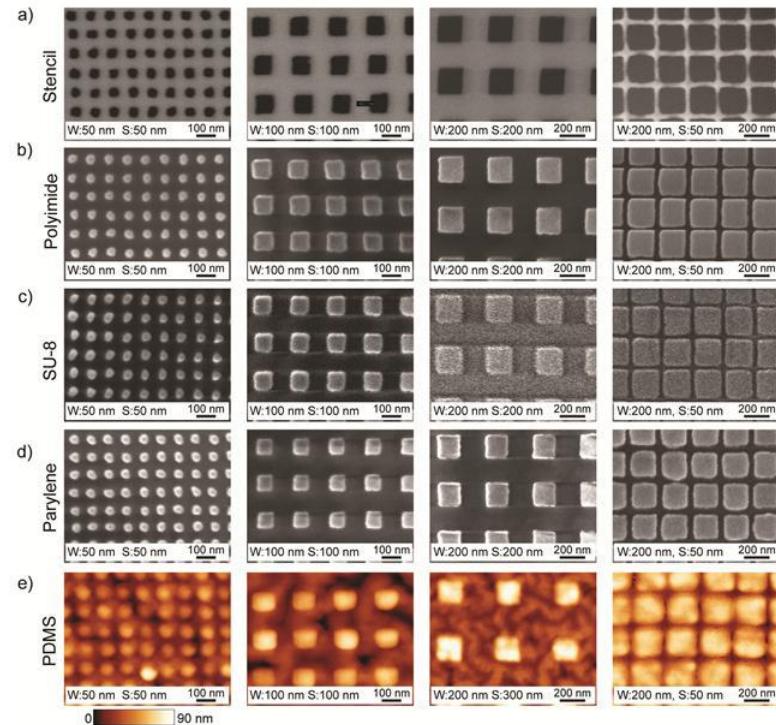
Metallic nanostructures stenciled onto ...

5 nm Ti / 50 nm Au

... silicon (Au clusters)



... polymer (no Au clusters)

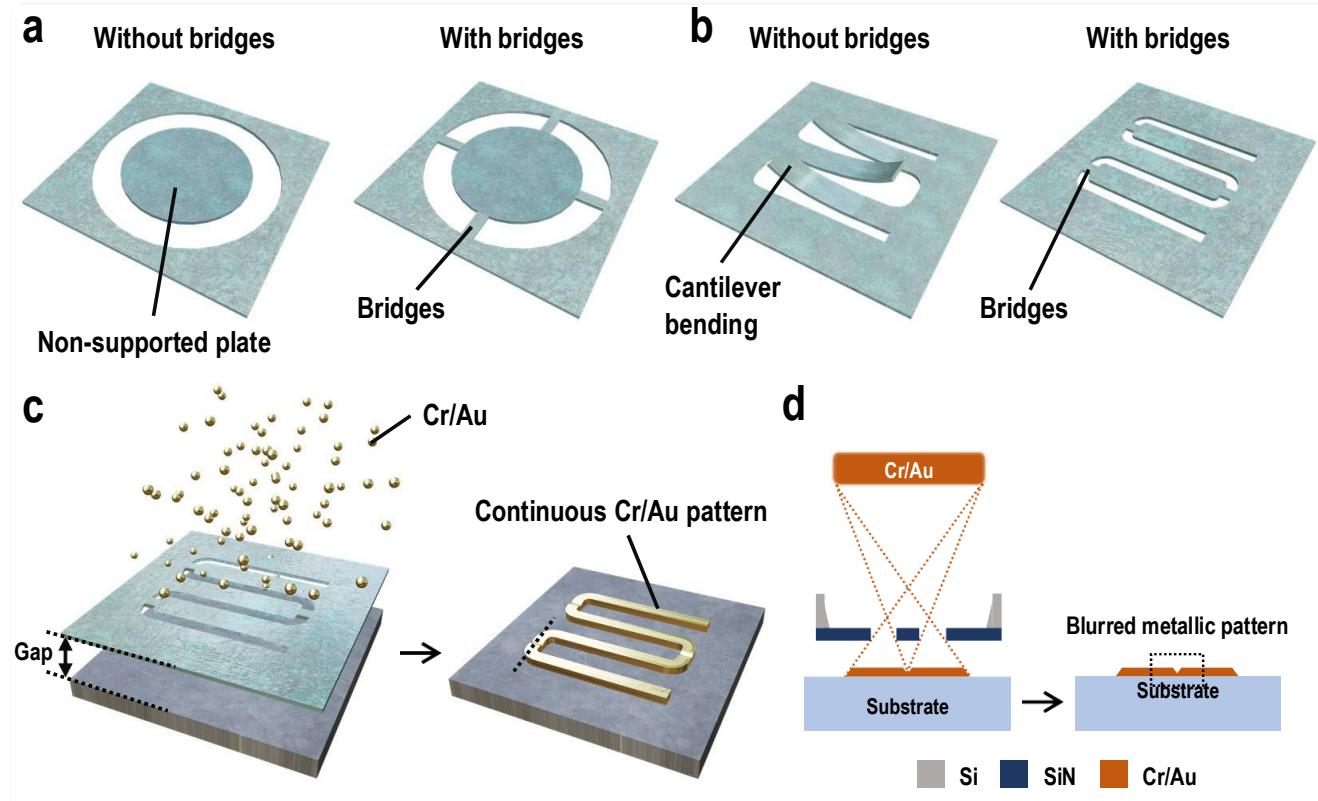


- Vazquez-Mena et al, ACS Nano (2010); ACS Nano (2012)

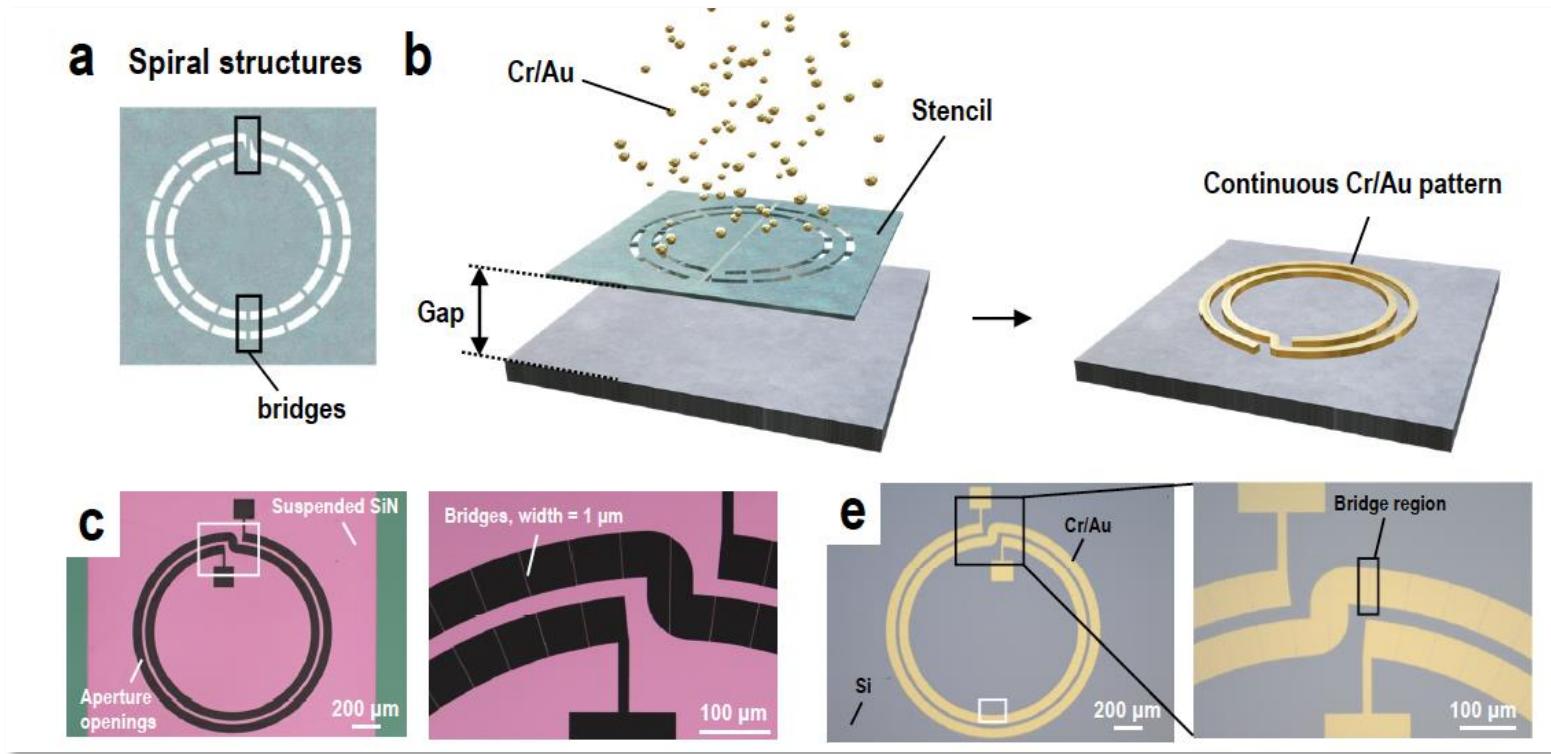


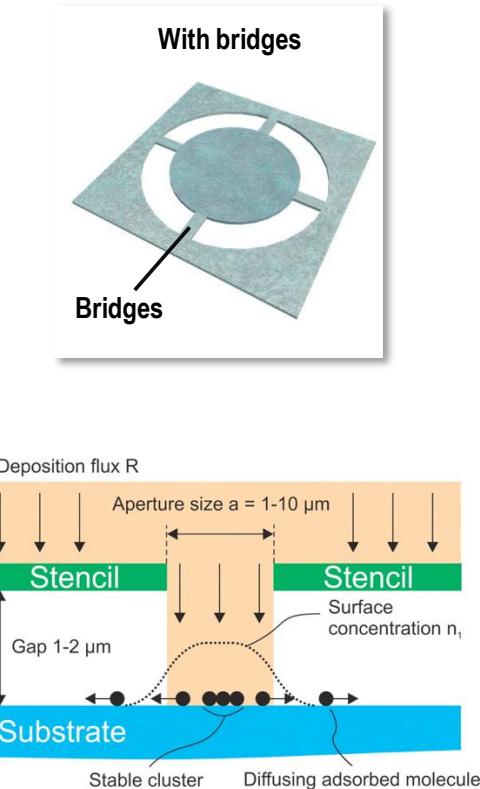
STENCIL
0123456789

Bridge stencils (micro)



Split ring resonator on flexible substrate





Nano stencil lithography

Take home message

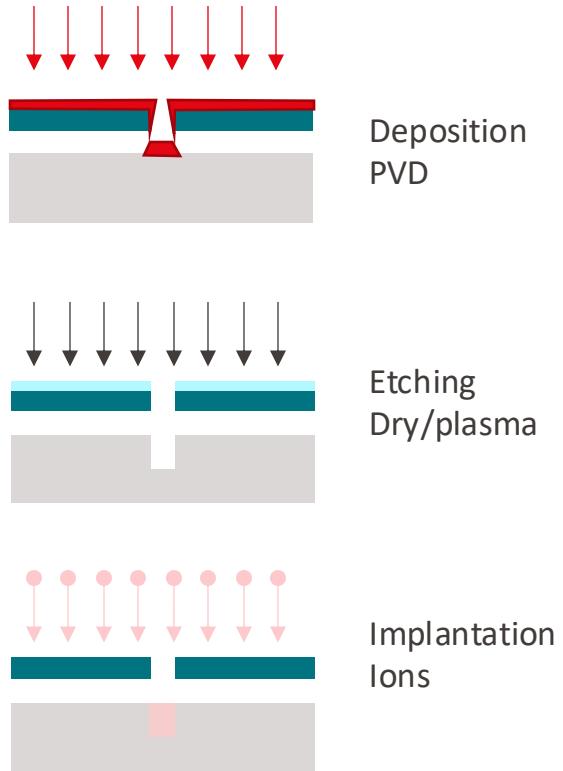
Fast, parallel, scalable patterning
without any wet stuff

Vacuum clean interfaces

Limits and remedies

Opportunities

Compare the different stencil applications



Deposition
PVD

Etching
Dry/plasma

Implantation
Ions